

N-Channel Power MOSFET

Product Summary

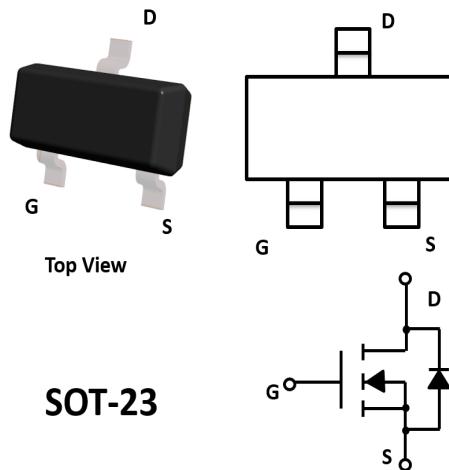
- V_{DS} 30V
- I_D 5.6A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <29 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <40 mohm

General Description

- Trench Power LV MOSFET technology
- High density cell design for low $R_{DS(ON)}$
- High Speed switching

Applications

- Battery protection
- Load switch
- Power management



■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	30	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current <small>$T_A=25^\circ C$ @ Steady State</small>	I_D	5.6	A
		4.5	
Pulsed Drain Current ^A	I_{DM}	30	A
Total Power Dissipation @ $T_A=25^\circ C$	P_D	1.2	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	104	$^\circ C / W$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ C$

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.5	2.2	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5.6\text{A}$		21	29	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=5.0\text{A}$		27	40	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=5.6\text{A}, V_{\text{GS}}=0\text{V}$		0.8	1.2	V
Maximum Body-Diode Continuous Current	I_{S}				5.6	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		490		pF
Output Capacitance	C_{oss}			92		
Reverse Transfer Capacitance	C_{rss}			68		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, I_{\text{D}}=5.6\text{A}$		5.2		nC
Gate Source Charge	Q_{gs}			0.9		
Gate Drain Charge	Q_{gd}			1.3		
Turn-on Delay Time	$t_{\text{D(on)}}$	$V_{\text{GS}}=4.5\text{V}, V_{\text{DD}}=15\text{V}, I_{\text{D}}=1\text{A}, R_{\text{GEN}}=2.8\Omega$		4.5		ns
Turn-on Rise Time	t_{r}			2.5		
Turn-off Delay Time	$t_{\text{D(off)}}$			14.5		
Turn-off Fall Time	t_{f}			3.5		

A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

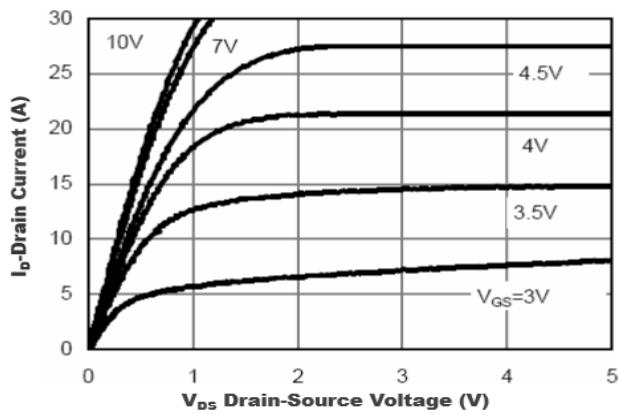


Figure1. Output Characteristics

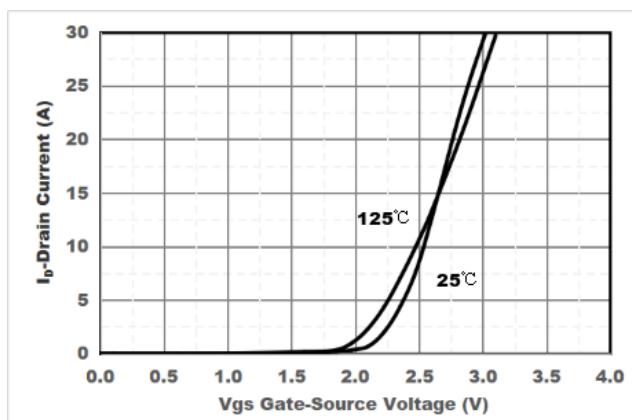


Figure2. Transfer Characteristics

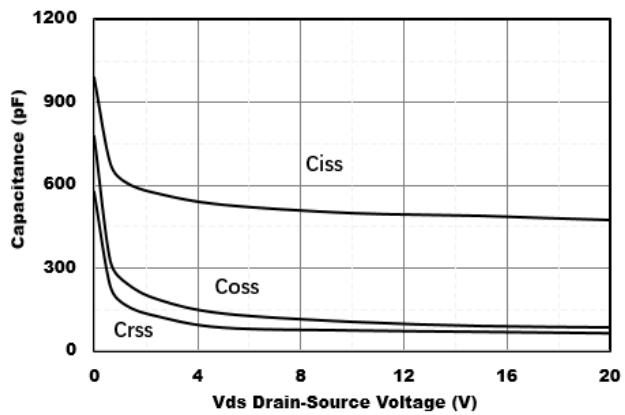


Figure3. Capacitance Characteristics

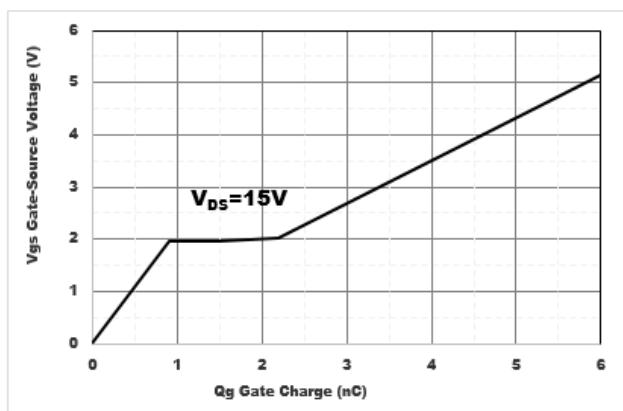


Figure4. Gate Charge

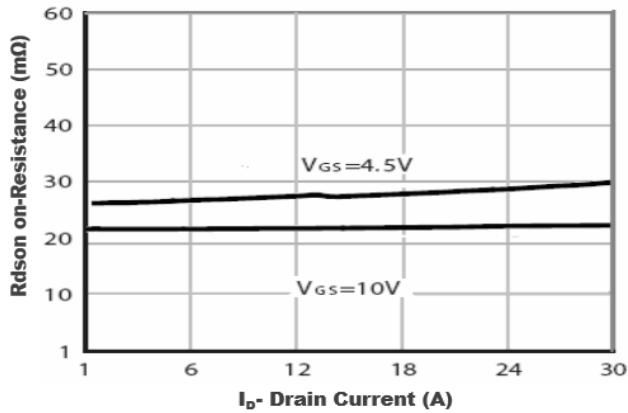


Figure5. Drain-Source on Resistance

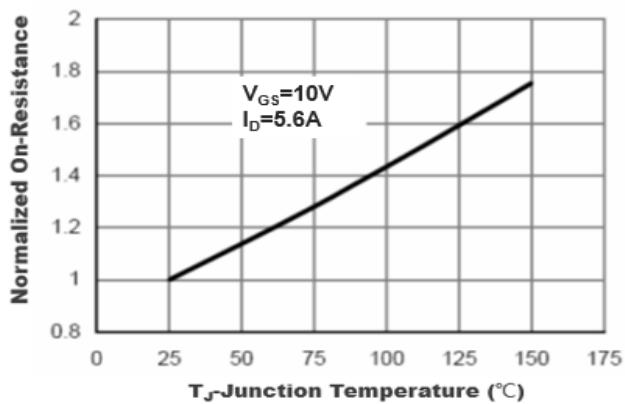


Figure6. Drain-Source on Resistance

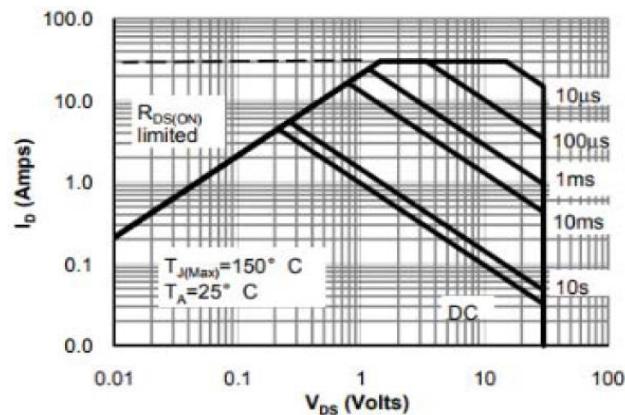


Figure7. Safe Operation Area

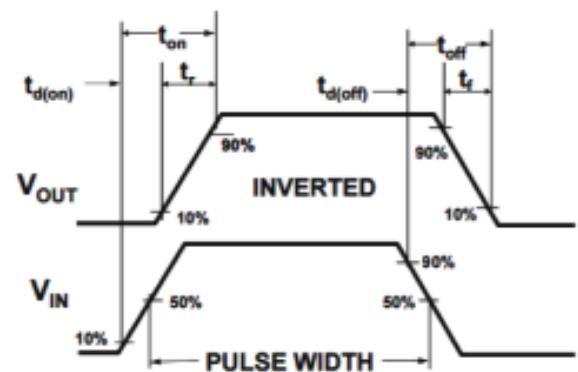
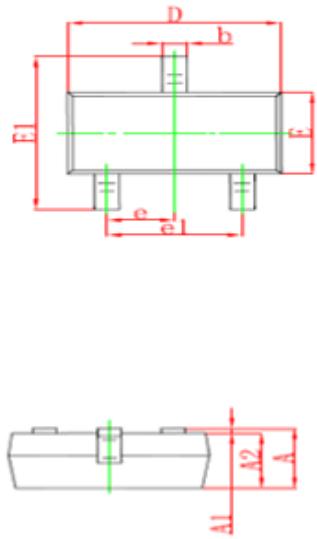


Figure8. Switching wave

■ SOT-23 Package information

Symbol	Dimensions in Millimeter		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0 °	8 °	0 °	8 °